

MACOM

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13/JAN/2025

Richardson RFPD, Inc.
2001 Butterfield Road, Suite 1800
Downers Grove, Illinois 60515

ATTN: Quality/Purchasing Manager

PCN-01825

Subject: Relocation of assembly for QFN, LGA, BGA, MIS and Module package to a new plant. (Unisem Gopeng Plant).

Dear Valued Customer,

MACOM Technology Solutions has a goal of providing redundant manufacturing capability for increased surge capacity as well as an uninterrupted supply chain. In alignment with this goal, we are pleased to announce an additional assembly and inspection site for the part listed in the next page.

The changes involved all devices built at our long-standing Contract Manufacturer, Unisem (M) Berhad under product group of QFN, LGA, BGA, MIS and Module package. Unisem is a valued, high-quality manufacturing partner for many MACOM products. To enable this product group to expand the manufacturing capacity to meet our customer demand, a new plant has been built and qualified. Qualification data will be available upon request.

Existing plant : Unisem Simpang Pulai Plant, Ipoh, Perak.

New plant : Unisem Gopeng Plant, Ipoh, Perak.

In accordance with MACOM Technology Solutions' customer notification policy, you are receiving this notice because you have purchased one or more of the products listed in the next page.

Sincerely,

Paul Wade
Product Line Manager
Diodes Business Unit
MACOM Technology Solutions, Inc.
E-mail: michael.napolitano@macom.com

PCN Number: PCN-01822		PCN Date: 10/Jan/2025
Title: Relocation of assembly for QFN, LGA, BGA, MIS and Module package to a new plant. (Unisem Gopeng Plant).		
Proposed 1st Ship Date: Shipments of the parts begins from March 2025 based on customer demand		Estimated Sample Availability: Samples upon request
Change Type:		
Assembly Site X	Design	Electrical Specification
Test Site	Assembly Process	Mechanical Specification
Test Process	Assembly Materials	Packing/Shipping/Labeling
PCN Details		
Description of Change:		
Relocation of assembly for QFN, LGA, BGA, MIS and Module package to a new plant (Unisem Gopeng Plant). There is no change to the form, fit, materials or performance of the device as a result of this change.		
Reason for Change:		
To enable this product group to expand the manufacturing capacity to meet our customer demand.		
Products Affected:		
Per the Appendix		
Anticipated impact on Fit, Form, Function:		
Form, Fit and Function unaffected.		
Changes to product identification resulting from this PCN:		
None		

Appendix : Affected devices (DIODES)

DEVICE	PACKAGE	BU
MADR-010574-000100	16SLP(7X7)-NP-HD	Diode
MASW-011071	44SLP(7X7)-NP-HD	Diode